ZP60-500

Positive Temperature Coefficient

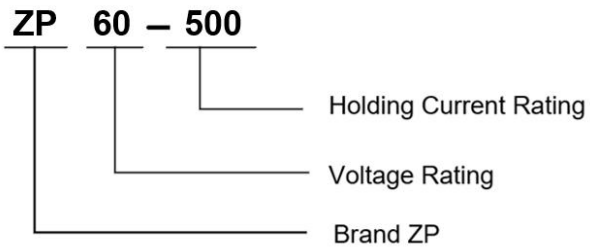
Features

- Radial leaded devices
- Over-current protection
- High voltage surge capabilities
- Available in lead-free version
- Meets MSL level 1, per J-STD-020
- Flame retardant epoxy polymer insulating material meets UL94 V-0 requirement
- Operating Temperature: -40℃~+85℃

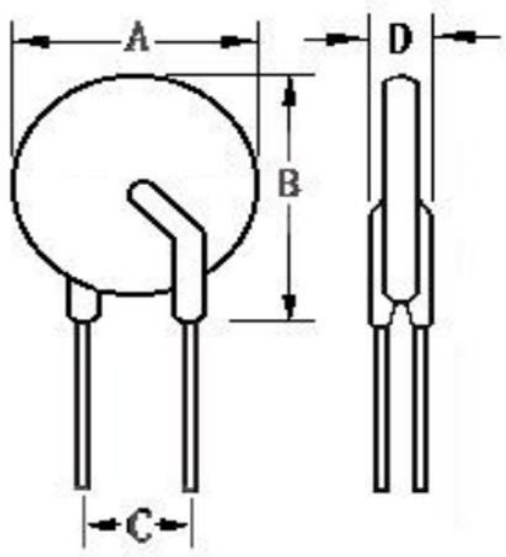
Applications

- USB hubs,ports and peripherals
- IT equipment
- Access network equipment
- Central office equipment
- ISDN and xDSL equipments
- Phone set and fax machine
- LAN/WAN and VOIP cards

Part Number Code and Making



Dimensions (unit:mm)



Symbol	Dimension	
	Millimeters	
	Min.	Max.
A	--	26.0
B	--	29.5
C	9.7	10.7
D	--	3.1
Lead	0.8	

Electrical Characteristics (T_A=25℃ unless otherwise noted)

Part Number	I_H (A)	I_T (A)	U_{Max} (V)	I_{Max} (A)	P_{DTYP} (W)	Time-To-trip		R_{Min} (Ω)	R_{Max} (Ω)	R_{1Max} (Ω)
						I_{Trip}(A)	T_{Max}(S)			
ZP60-500	5.0	10.0	60	40	3.2	15	25	0.025	0.05	0.06

I_H = Hold current: maximum current device will pass without tripping in 25°℃ still air.

I_T =Trip current minimum current at which the device will trip in 25 ℃ still air.

U_{Max}= Maximum voltage device can withstand without damage at rated current (I_{max}).

I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max}).

P_{DTYP} = Typical Power dissipated from device when in the tipped state at 25 ℃ still air.

R_{min} = Minimum resistance of device in initial(un-soldered) state.

R_{Max} =Maximum resistance of device in initial (un-soldered) state.

R_{1max} = Maximum resistance of device at 25 ℃ measured one hour after tripping or reflow soldering of 260 ℃ for 20 sec.

Ratings and Characteristic Curves (T_A=25℃ unless otherwise noted)

Figure 1. Thermal Derating Curve

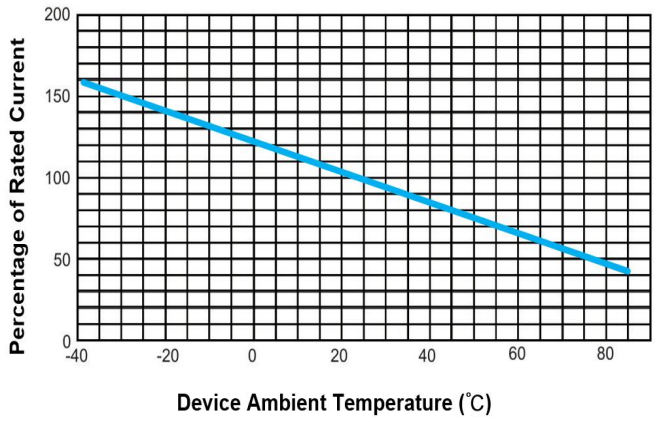
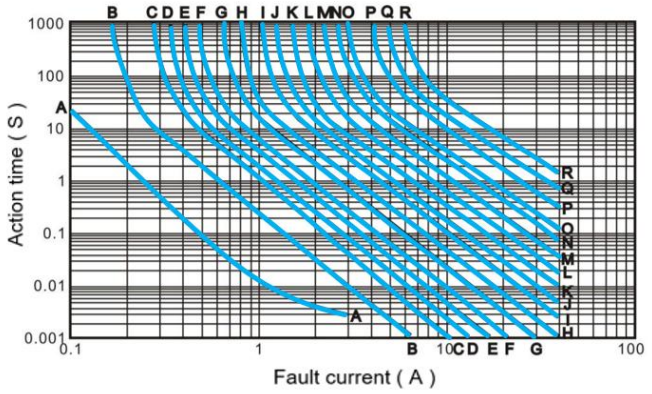
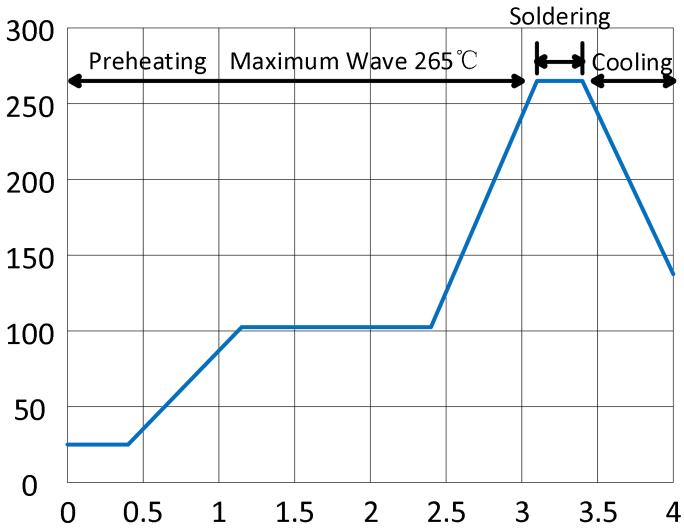


Figure 2. Typical action time curve



Part Number	Ambient Operation Temperature								
	-40℃	-20℃	0℃	25℃	40℃	50℃	60℃	70℃	85℃
ZP60-500	7.75	6.80	5.95	5.00	4.05	3.60	3.15	2.70	2.00

Wave Soldering Parameters



Condition	Lead-free Assembly
Peak Temperature	265℃
Dipping Time	10 seconds
Soldering	1 time